XHP™3 module with Trench/Fieldstop IGBT3 and Emitter Controlled 3 diode

Features

- Electrical features
  - High dynamic robustness
  - Low V_{CEsat}
  - Trench IGBT 3
- Mechanical features
  - Package with CTI > 600
  - Package with enhanced insulation of 10.4kV AC 10s
  - AlSiC base plate for increased thermal cycling capability
  - Extended storage temperature down to T_{stg} = -55°C
  - High creepage and clearance distances
  - Housing material compliant with the classification R23 (HL3) of the EN45545-2 “Fire protection of railway vehicles”

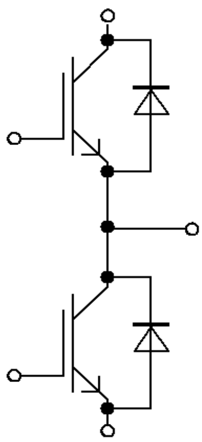
Potential applications

- Traction drives
- Medium voltage converters

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description



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1 Package

Table 1 Insulation Coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, f = 50 Hz, t = 10 s	10.4	kV
Partial discharge extinction voltage	V_{isol}	RMS, f = 50 Hz, Q_{PD} typ. 10 pC	5.1	kV
DC stability	$V_{CE(D)}$	T_{vj}=25°C, 100 Fit	3800	V
Material of module baseplate			AlSiC	
Creepage distance	d_{Creep}	terminal to heatsink	53.0	mm
Clearance	d_{Clear}	terminal to heatsink	26.0	mm
Comperative tracking index	CTI		> 600	

Table 2 Characteristic Values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Stray inductance module	L_{sCE}				25		nH
Module lead resistance, terminals - chip	$R_{AA'+CC'}$	T_C=25°C, per switch			0.33		mΩ
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	T_C=25°C, per switch			0.42		mΩ
Storage temperature	T_{stg}			-55		125	°C
Mounting torque for modul mounting	M	- Mounting according to valid application note	M6, Screw	4.25		5.75	Nm
Terminal connection torque	M	- Mounting according to valid application note	M3, Screw	0.9		1.1	Nm
			M8, Screw	8		10	
Weight	G				700		g

2 IGBT, Inverter

Table 3 Maximum Rated Values

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CES}		T_{vj} = -50 °C	5900	V
			T_{vj} = 125 °C	6500	
Continous DC collector current	I_{CDC}	$T_{vj\,max}$ = 125 °C	T_C = 80 °C	225	A

Table 3 **Maximum Rated Values (continued)**

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak collector current	I_{CRM}	t_P = 1 ms	450	A
Gate-emitter peak voltage	V_{GES}		±20	V

Table 4 **Characteristic Values**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\ sat}$	I_C = 225 A, V_{GE} = 15 V	T_{vj} = 25 °C		3.00	3.40	V
			T_{vj} = 125 °C		3.70	4.20	
Gate threshold voltage	V_{GEth}	I_C = 33 mA, V_{CE} = V_{GE}, T_{vj} = 25 °C		5.40	6	6.60	V
Gate charge	Q_G	V_{GE} = ±15 V, V_{CE} = 3600 V			10.5		µC
Internal gate resistor	R_{Gint}	T_{vj} = 25 °C			0.67		Ω
Input capacitance	C_{ies}	f = 100 kHz, T_{vj} = 25 °C, V_{CE} = 25 V, V_{GE} = 0 V			65.6		nF
Reverse transfer capacitance	C_{res}	f = 100 kHz, T_{vj} = 25 °C, V_{CE} = 25 V, V_{GE} = 0 V			1		nF
Collector-emitter cut-off current	I_{CES}	V_{CE} = 6500 V, V_{GE} = 0 V	T_{vj} = 25 °C			5	mA
Gate-emitter leakage current	I_{GES}	V_{CE} = 0 V, V_{GE} = 20 V, T_{vj} = 25 °C				400	nA
Turn-on delay time (inductive load)	t_{don}	I_C = 225 A, V_{CE} = 3600 V, V_{GE} = ±15 V, R_{Gon} = 4.7 Ω	T_{vj} = 25 °C		0.240		µs
			T_{vj} = 125 °C		0.240		
Rise time (inductive load)	t_r	I_C = 225 A, V_{CE} = 3600 V, V_{GE} = ±15 V, R_{Gon} = 4.7 Ω	T_{vj} = 25 °C		0.070		µs
			T_{vj} = 125 °C		0.080		

Table 4 **Characteristic Values (continued)**

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Turn-off delay time (inductive load)	t_{doff}	I_C = 225 A, V_{CE} = 3600 V, V_{GE} = ±15 V, R_{Goff} = 22 Ω	T_{vj} = 25 °C		6.000		µs
			T_{vj} = 125 °C		6.400		
Fall time (inductive load)	t_f	I_C = 225 A, V_{CE} = 3600 V, V_{GE} = ±15 V, R_{Goff} = 22 Ω	T_{vj} = 25 °C		0.950		µs
			T_{vj} = 125 °C		2.000		
Turn-on energy loss per pulse	E_{on}	I_C = 225 A, V_{CE} = 3600 V, L_σ = 85 nH, V_{GE} = ±15 V, R_{Gon} = 4.7 Ω, di/dt = 2200 A/µs (T_{vj} = 125 °C)	T_{vj} = 25 °C		1230		mJ
			T_{vj} = 125 °C		1710		
Turn-off energy loss per pulse	E_{off}	I_C = 225 A, V_{CE} = 3600 V, L_σ = 85 nH, V_{GE} = ±15 V, R_{Goff} = 22 Ω, dv/dt = 2100 V/µs (T_{vj} = 125 °C)	T_{vj} = 25 °C		875		mJ
			T_{vj} = 125 °C		1170		
SC data	I_{SC}	V_{GE} ≤ 15 V, V_{CC} = 4500 V, $V_{CEmax}=V_{CES}-L_{sCE}$*di/dt	t_P ≤ 10 µs, T_{vj} = 125 °C		1300		A
Thermal resistance, junction to case	R_{thJC}	per IGBT				0.0291	K/W
Thermal resistance, case to heatsink	R_{thCH}	per IGBT, λ_{Paste}= 1 W /(m*K) / λ_{grease}= 1 W/(m*K)			0.0213		K/W
Temperature under switching conditions	$T_{vj\,op}$			-50		125	°C

3 Diode, Inverter

Table 5 Maximum Rated Values

Parameter	Symbol	Note or test condition		Values	Unit
Repetitive peak reverse voltage	V_{RRM}		T_{vj} = -50 °C	5900	V
			T_{vj} = 125 °C	6500	
Continous DC forward current	I_F			225	A
Repetitive peak forward current	I_{FRM}	t_P = 1 ms		450	A
I^2t - value	I^2t	t_P = 10 ms, V_R = 0 V	T_{vj} = 125 °C	45.2	kA^2s
Maximum power dissipation	P_{RQM}	T_{vj} = 125 °C		1000	kW
Minimum turn-on time	t_{onmin}			10	µs

Table 6 Characteristic Values

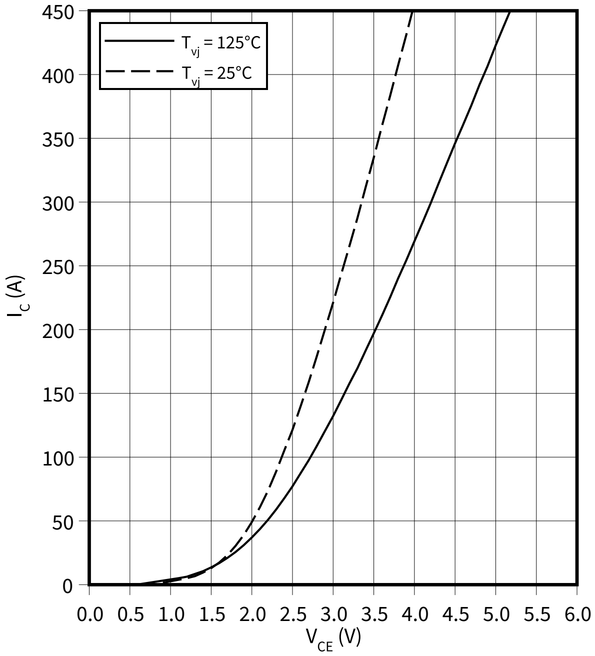
Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Forward voltage	V_F	I_F = 225 A, V_{GE} = 0 V	T_{vj} = 25 °C		3.10	3.55	V
			T_{vj} = 125 °C		2.85	3.25	
Peak reverse recovery current	I_{RM}	V_R = 3600 V, I_F = 225 A, V_{GE} = -15 V, -di$_F$/dt = 2200 A/µs (T_{vj} = 125 °C)	T_{vj} = 25 °C		405		A
			T_{vj} = 125 °C		365		
Recovered charge	Q_r	V_R = 3600 V, I_F = 225 A, V_{GE} = -15 V, -di$_F$/dt = 2200 A/µs (T_{vj} = 125 °C)	T_{vj} = 25 °C		255		µC
			T_{vj} = 125 °C		505		
Reverse recovery energy	E_{rec}	V_R = 3600 V, I_F = 225 A, V_{GE} = -15 V, -di$_F$/dt = 2200 A/µs (T_{vj} = 125 °C)	T_{vj} = 25 °C		450		mJ
			T_{vj} = 125 °C		1070		
Thermal resistance, junction to case	R_{thJC}	per diode				0.0513	K/W
Thermal resistance, case to heatsink	R_{thCH}	per diode, λ_{Paste}= 1 W /(m*K) / λ_{grease}= 1 W/(m*K)			0.0242		K/W
Temperature under switching conditions	$T_{vj\,op}$			-50		125	°C

4 Characteristics diagrams

output characteristic (typical), IGBT, Inverter

$I_C = f(V_{CE})$

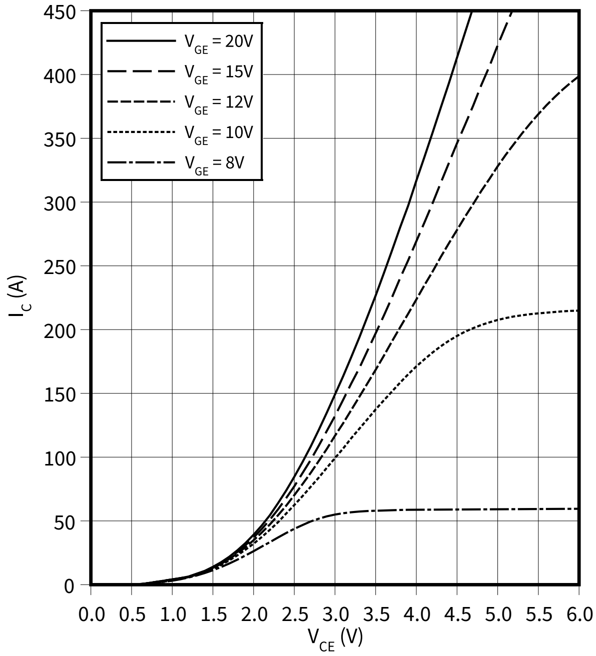
$V_{GE} = 15$ V



output characteristic (typical), IGBT, Inverter

$I_C = f(V_{CE})$

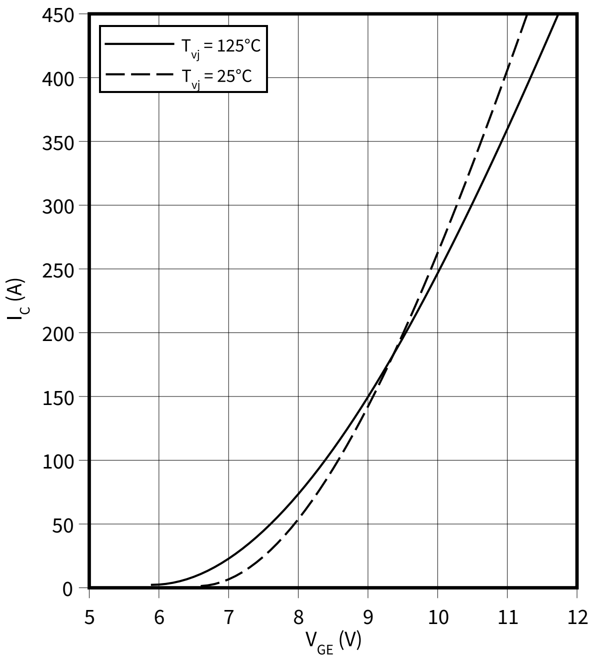
$T_{vj} = 125$ °C



transfer characteristic (typical), IGBT, Inverter

$I_C = f(V_{GE})$

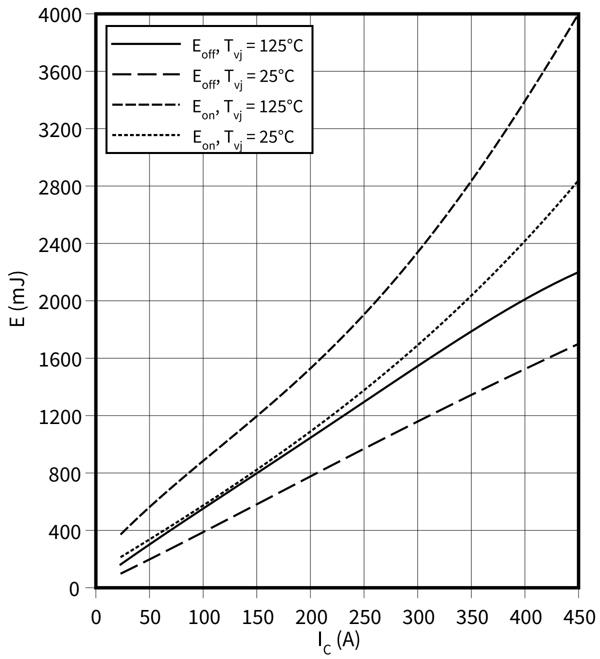
$V_{CE} = 20$ V



switching losses (typical), IGBT, Inverter

$E = f(I_C)$

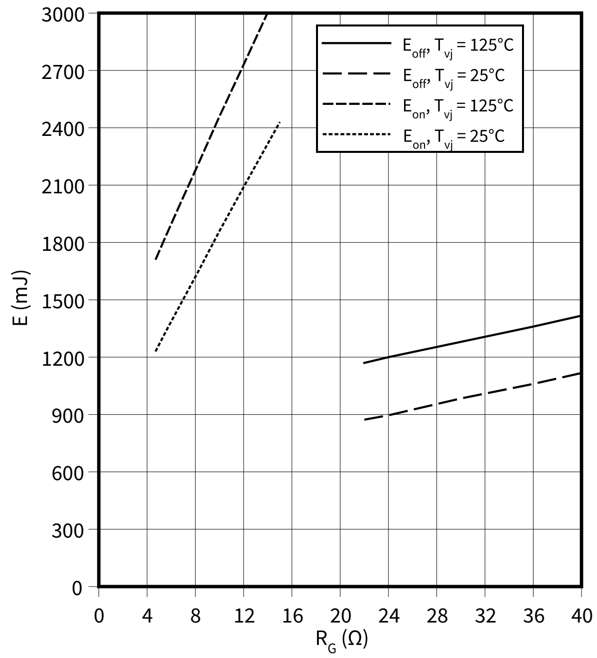
$R_{Goff} = 22\ \Omega$, $R_{Gon} = 4.7\ \Omega$, $V_{CE} = 3600$ V, $V_{GE} = \pm 15$ V



switching losses (typical), IGBT, Inverter

$E = f(R_G)$

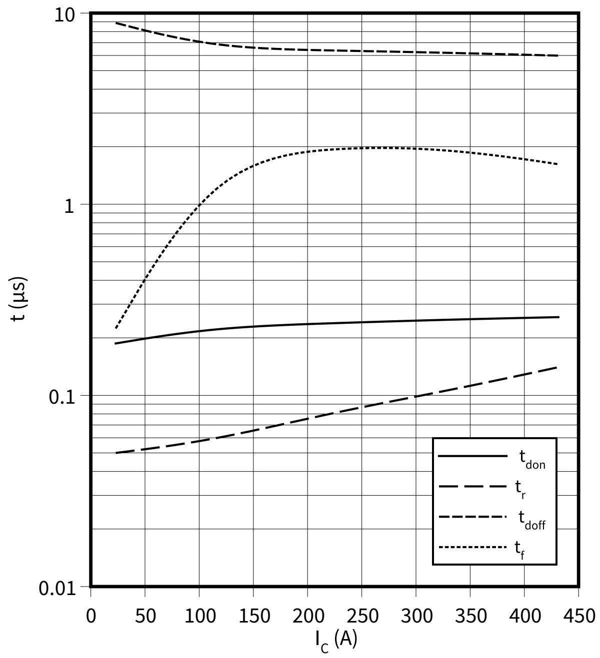
I_C = 225 A, V_{CE} = 3600 V, V_{GE} = ± 15 V



switching times (typical), IGBT, Inverter

$t = f(I_C)$

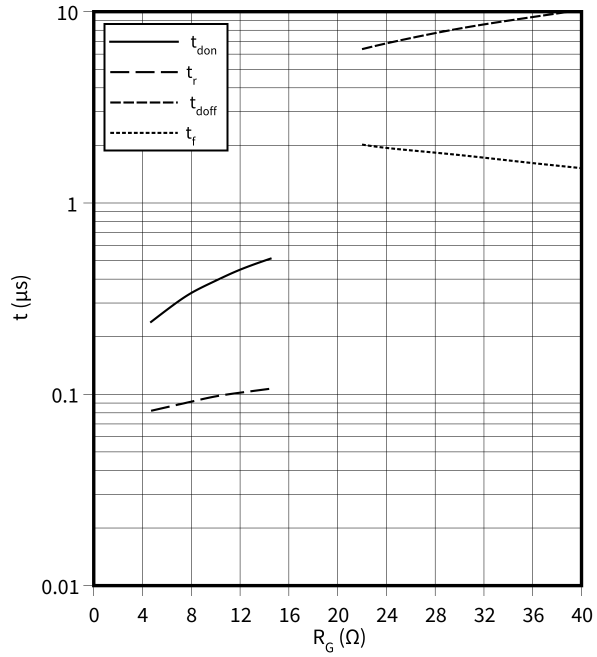
R_{Goff} = 22 Ω, R_{Gon} = 4.7 Ω, V_{CE} = 3600 V, V_{GE} = ± 15 V, T_{vj} = 125 °C



switching times (typical), IGBT, Inverter

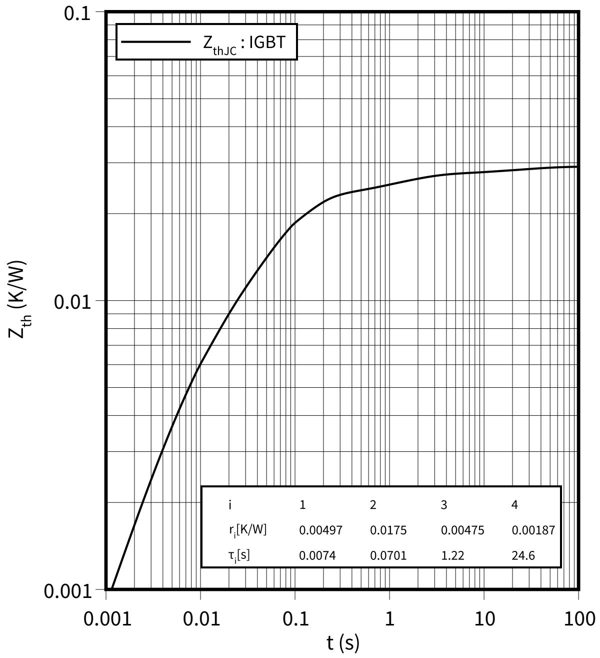
$t = f(R_G)$

I_C = 225 A, V_{CE} = 3600 V, V_{GE} = ± 15 V, T_{vj} = 125 °C



transient thermal impedance, IGBT, Inverter

$Z_{th} = f(t)$

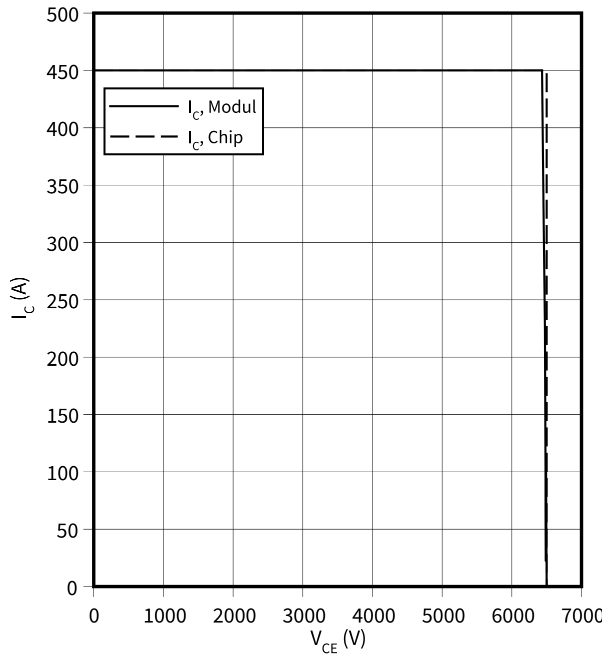


i	1	2	3	4
r_i[K/W]	0.00497	0.0175	0.00475	0.00187
τ_i[s]	0.0074	0.0701	1.22	24.6

reverse bias safe operating area (RBSOA), IGBT, Inverter

$I_C = f(V_{CE})$

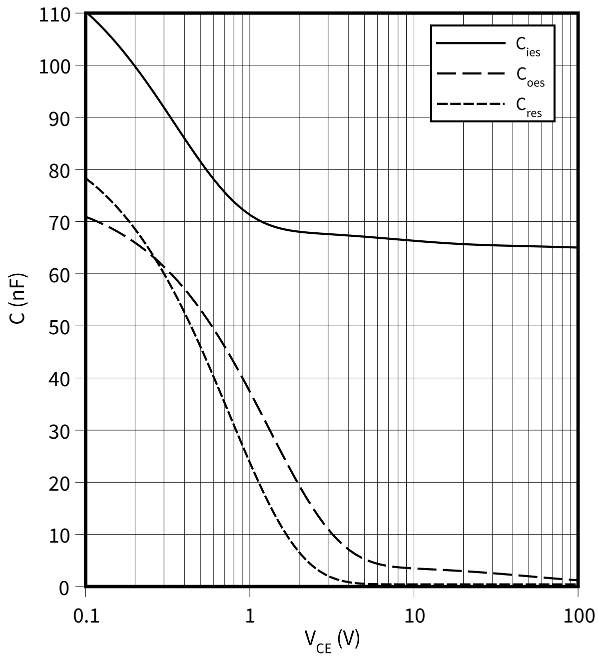
$R_{Goff} = 22\ \Omega$, $V_{GE} = \pm 15$ V, $T_{vj} = 125$ °C



capacity characteristic (typical), IGBT, Inverter

$C = f(V_{CE})$

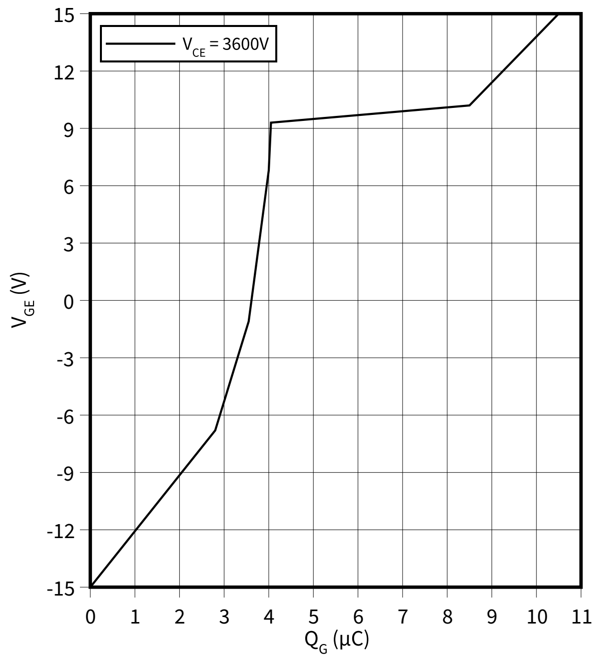
$f = 100$ kHz, $V_{GE} = 0$ V, $T_{vj} = 25$ °C



gate charge characteristic (typical), IGBT, Inverter

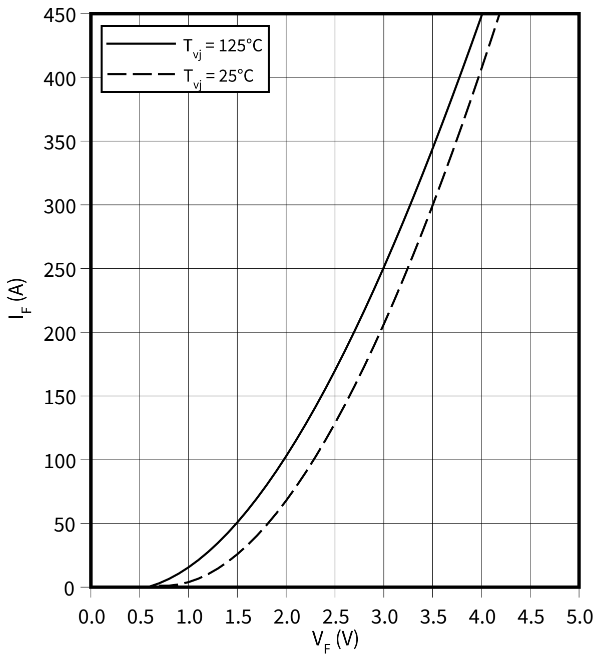
$V_{GE} = f(Q_G)$

$I_C = 225$ A, $T_{vj} = 25$ °C



forward characteristic (typical), Diode, Inverter

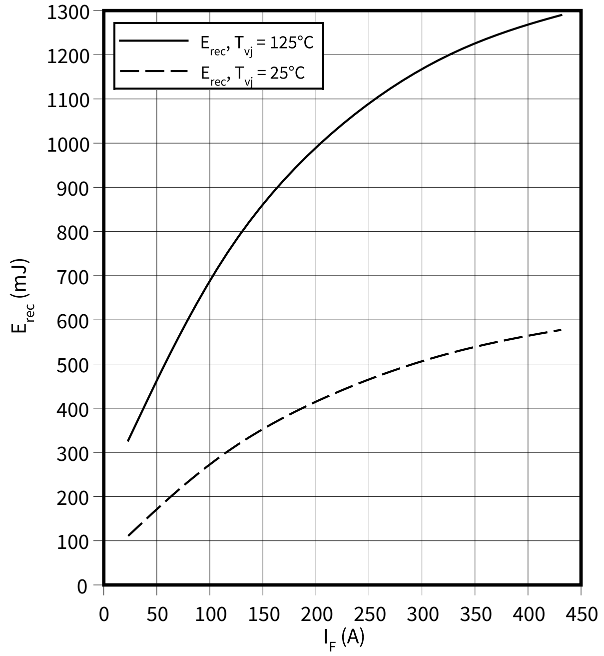
$I_F = f(V_F)$



switching losses (typical), Diode, Inverter

$E_{rec} = f(I_F)$

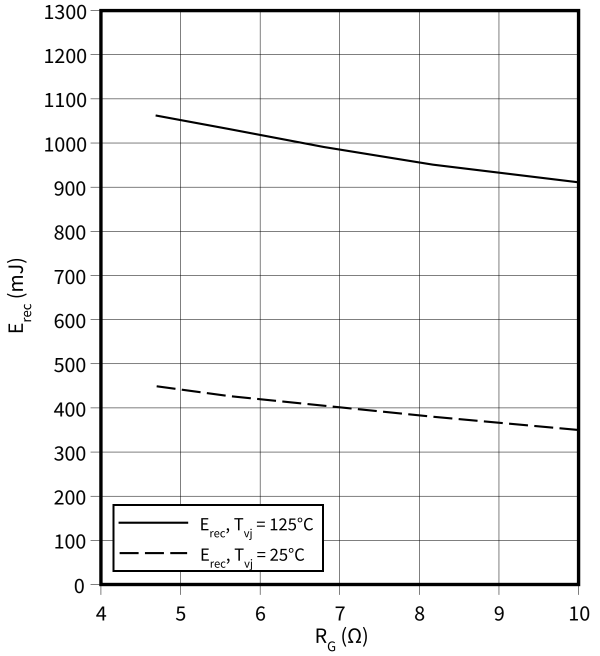
$R_{Gon} = 4.7\ \Omega$, $V_{CE} = 3600$ V



switching losses (typical), Diode, Inverter

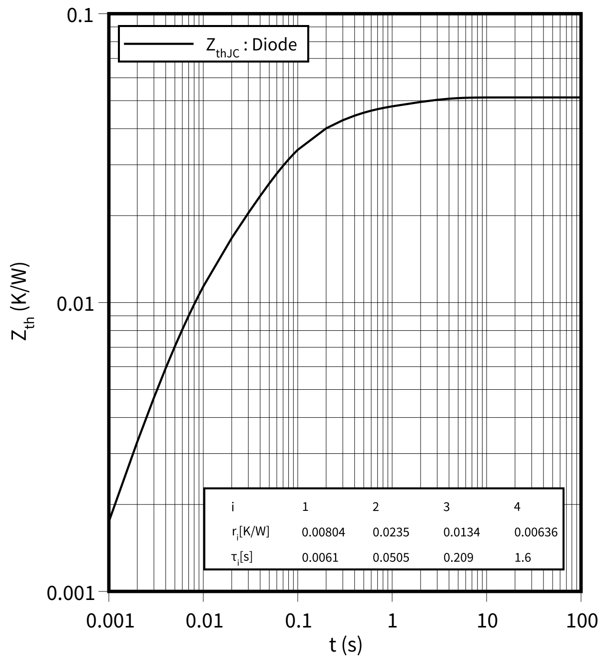
$E_{rec} = f(R_G)$

$V_{CE} = 3600$ V, $I_F = 225$ A



transient thermal impedance , Diode, Inverter

$Z_{th} = f(t)$

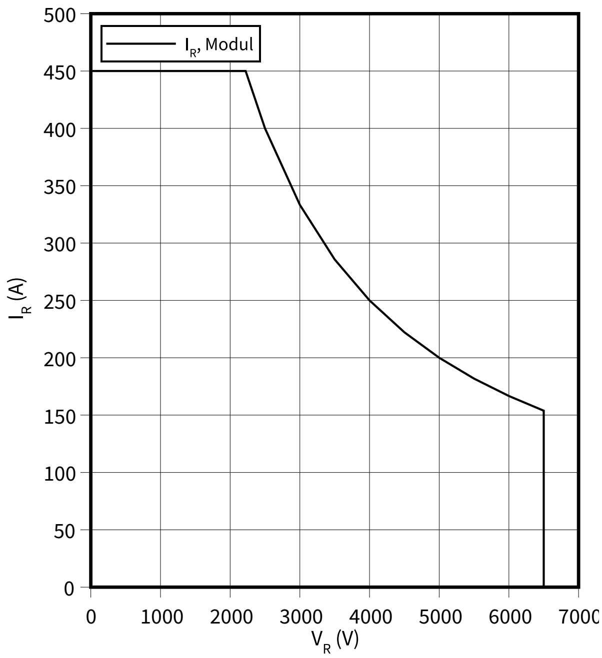


i	1	2	3	4
r_i[K/W]	0.00804	0.0235	0.0134	0.00636
τ_i[s]	0.0061	0.0505	0.209	1.6

safe operation area (SOA), Diode, Inverter

$I_R = f(V_R)$

$T_{vj} = 125$ °C



5 Circuit diagram

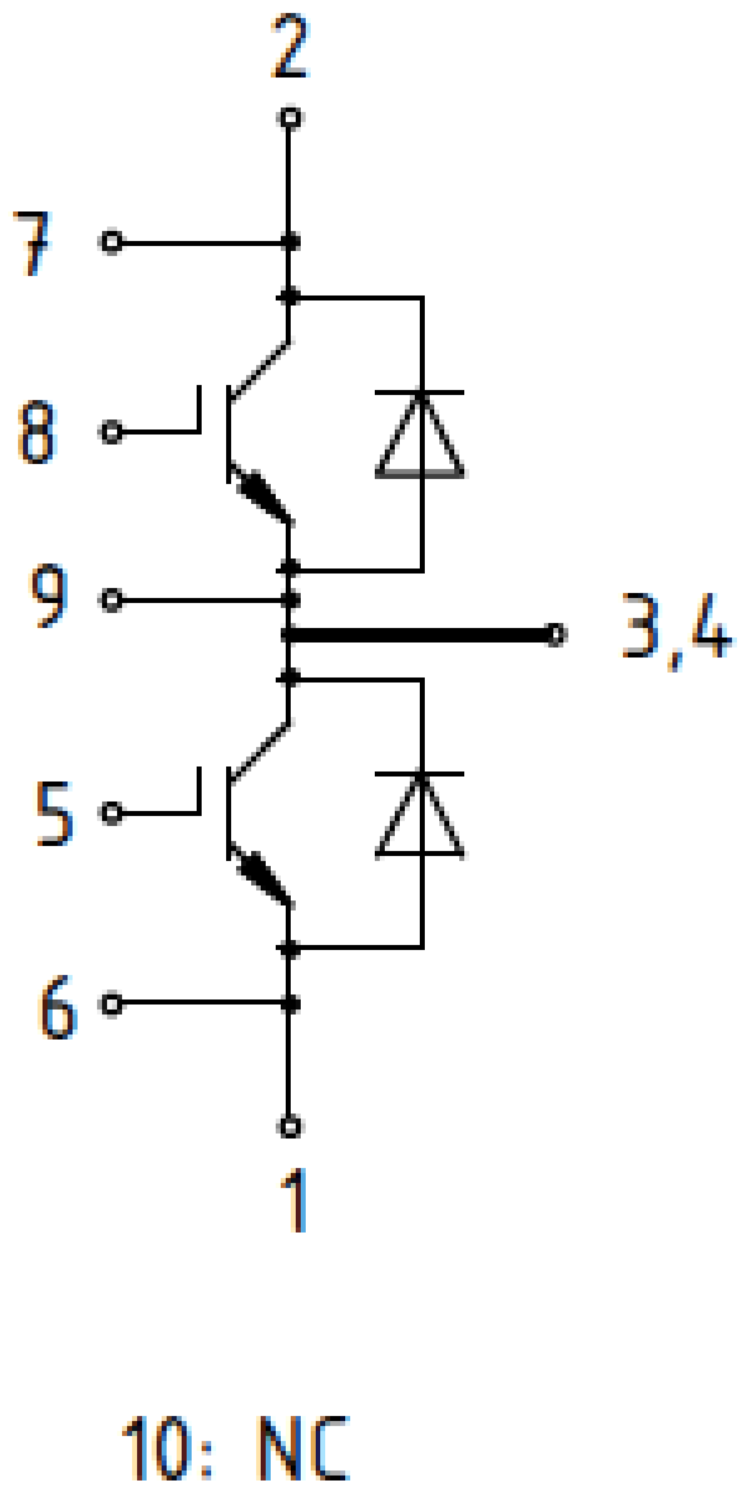


Figure 2

6 Package outlines

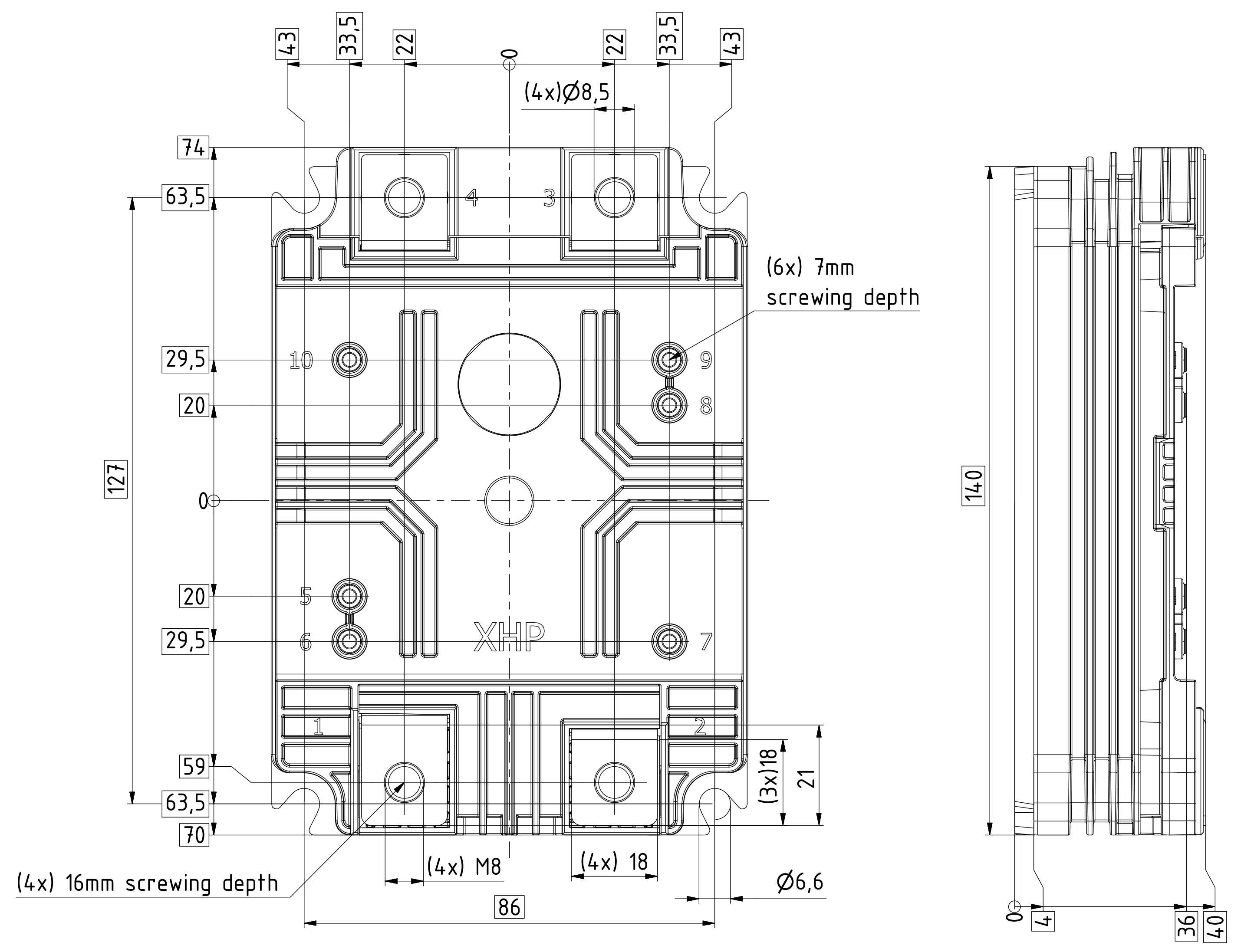


Figure 3

7 Module label code

Module label code			
Code format	Data Matrix		Barcode Code128
Encoding	ASCII text		Code Set A
Symbol size	16x16		23 digits
Standard	IEC24720 and IEC16022		IEC8859-1
Code content	*Content*	*Digit*	*Example*
	Module serial number	1 – 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 – 21	15
	Date code (production week)	22 – 23	30
Example	71549142846550549911530		71549142846550549911530

Figure 4

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